

## **Electronic Supplementary Information**

### **Atomic layer deposition of dielectric $Y_2O_3$ thin films from a homoleptic yttrium formamidinate precursor and water**

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## S1. EI-MS Spectra

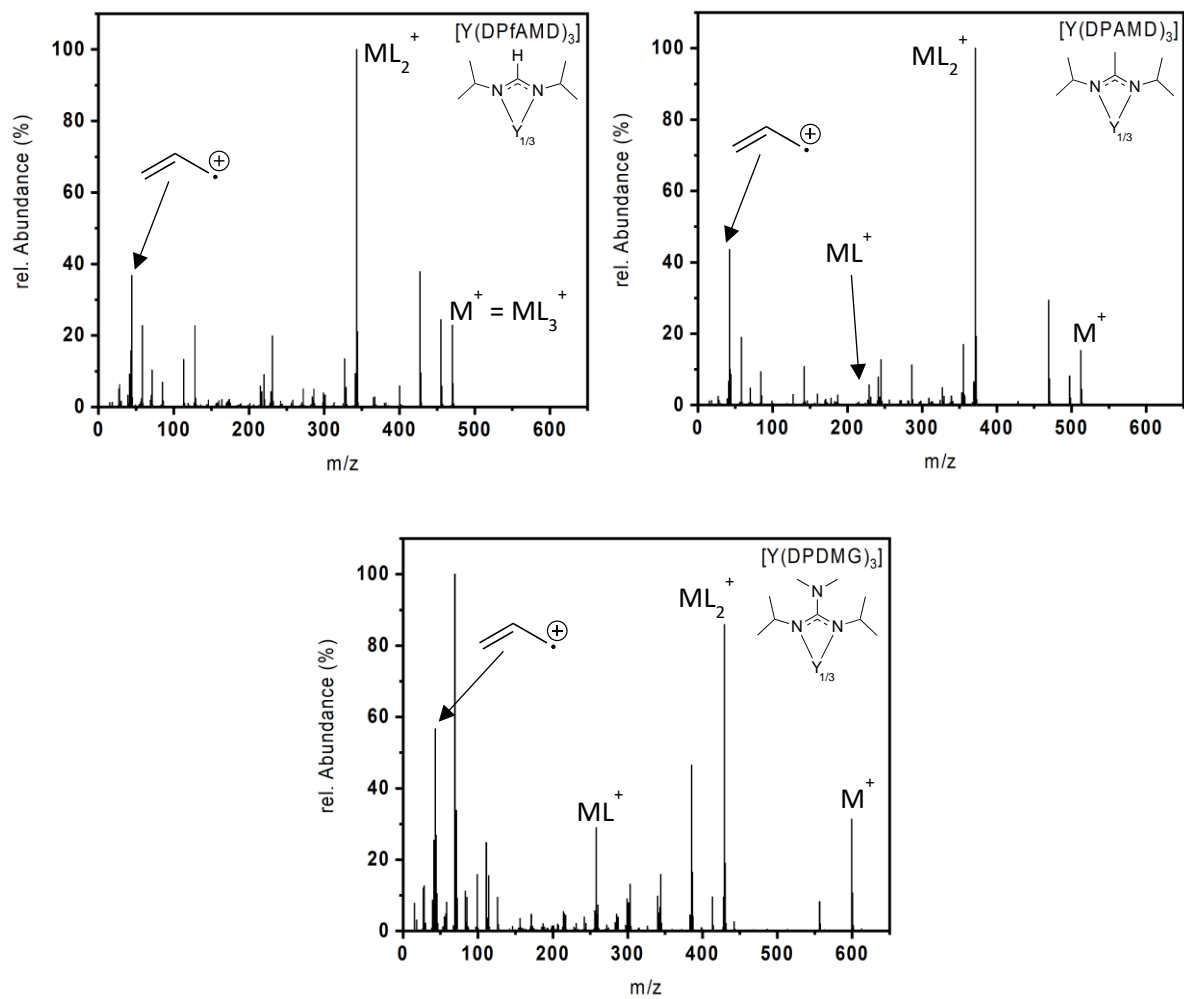


Figure S 1. EI-MS spectra with the fragmentation behavior for all three precursor molecules. The molecular peak ( $M^+$ ) is the peak with the highest observable  $m/z$  ratio in all spectra.<sup>[1-4]</sup>

### S3. ALD Saturation Studies

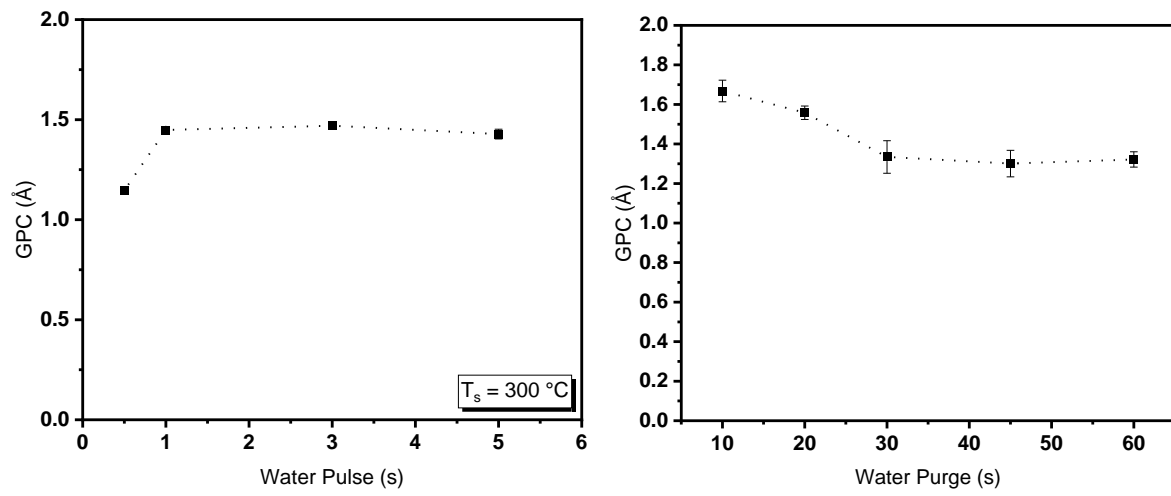


Figure S 2. Water saturation curves: Dependence of the GPC to water pulse length (left) and water purge length (right) for films deposited at 300 °C on Si(100).

## S4. Composition analysis through RBS/NRA

Table S1. Overview of the atomic percentage values for the light elements (C, N and O) obtained by NRA and for yttrium obtained by RBS at different substrate temperatures  $T_s$  resulting in different oxygen to yttrium ratios.

$T_s$ (°C)	C (at.%)	N (at.%)	O (at.%)	Y (at.%)	O/Y
100	19	1	71	9	7.7
125	6	0	69	24	2.8
150	5	1	66	28	2.3
175	4	0	67	28	2.4
200	2	0	65	33	2.0
225	1	2	64	33	2.0
250	1	0	65	33	2.0
275	< 1	1	64	35	1.8
300	< 1	< 1	63	37	1.7
300 <sup>(a)</sup>	< 1	< 1	59	40	1.5
325	< 1	2	61	37	1.6

. <sup>(a)</sup> Y<sub>2</sub>O<sub>3</sub> film thickness d = 470 nm using the same conditions as mentioned before.

## S5. X-ray Photoelectron Spectroscopy (XPS)

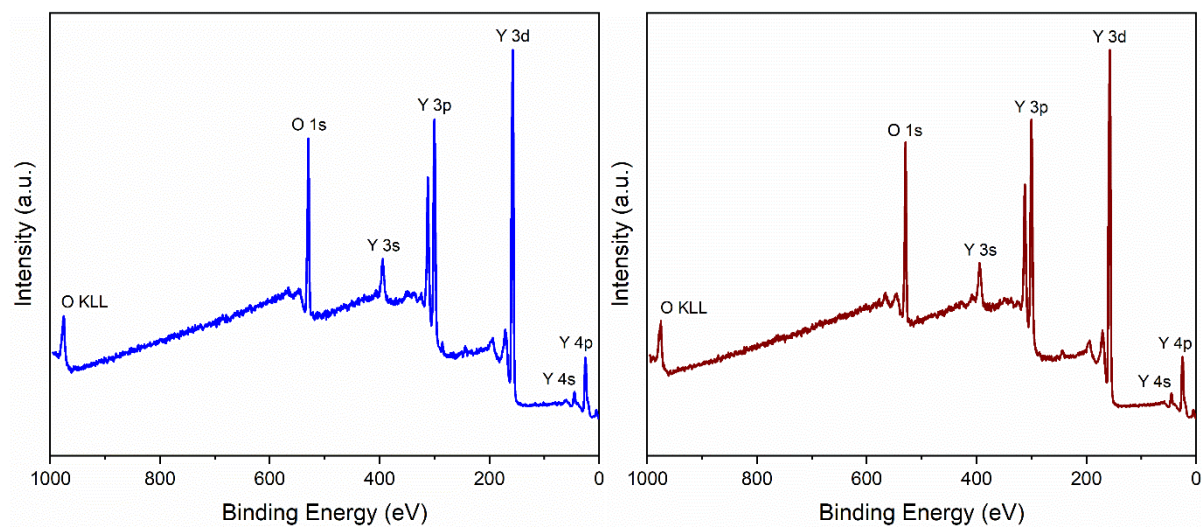


Figure S 3. XPS survey spectra for the as-introduced 40 nm  $Y_2O_3$  thin film on Si(100) deposited at 300 °C (left chart in blue) and for the 1 min  $Ar^+$  sputtered surface (right chart in red).

## S6. J-E Characteristics of the MIS Capacitors

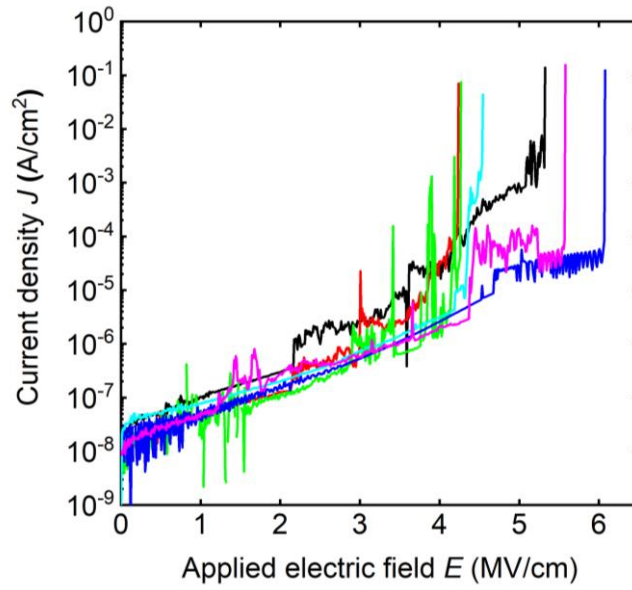


Figure S 4. Leakage current density  $J$  as a function of the electric field  $E$  for several MIS devices incorporating  $Y_2O_3$  ( $d = 24$  nm) deposited at  $T = 300$  °C. Each color represents a  $J$ - $E$  characteristic of an individual device with identical device geometries.

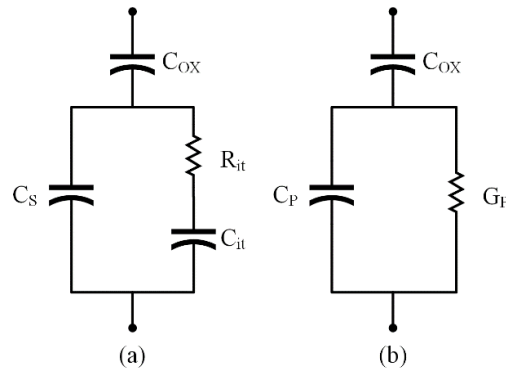


Figure S 5. Equivalent circuit of an MIS capacitor including interface-trap effect (reproduced from Nicollian and Goetzberger).<sup>[5]</sup>

Equations (1-3):

$$C_p = C_s + \frac{C_{it}}{1+(\omega\tau_{it})^2} \quad (1)$$

$$\frac{G_p}{\omega} = \frac{q\omega\tau_{it}D_{it}}{1+(\omega\tau_{it})^2} \quad (2)$$

$$D_{it} = \frac{2G_{p,max}}{q\omega_{max}} \quad (3)$$

## S7. References

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- [3] A. P. Milanov, K. Xu, S. Cwik, H. Parala, T. de los Arcos, H.-W. Becker, D. Rogalla, R. Cross, S. Paul, A. Devi, *Dalton Trans.* **2012**, *41*, 13936.
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